

A HIGH DENSITY, ZERO-HEIGHT, FREE FLOATING INTERCONNECT METHOD AND APPARATUS

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ABSTRACT OF THE DISCLOSURE

A method and circuit board assembly provide a zero interconnection height in a board-to-board interconnect while maintaining efficient space allocation for multiple axis connections by providing a floating connection in one plane thereby

- 10 enabling a connection in another plane. A method for interconnecting includes aligning a first circuit board having a first plurality of through-holes with a second circuit board having a second plurality of through-holes by matching the first plurality of through-holes with the second plurality of through-holes, the aligning providing an interconnection height of zero between the first circuit board and the second circuit
- 15 board, aligning at least one pass-through socket with the aligned combination of the first circuit board and second circuit board, the at least one pass-through socket including pass-through socket through-holes, and inserting one or more pins disposed on a pin header through the at least one pass-through socket, the first circuit board and the second circuit board. The method further includes floating one of the first circuit
- 20 board and the second circuit board prior to inserting the pin header, the floating enabling the first circuit board to interconnect with the second circuit board with a connector aligned along an axis different from the pin header.